

# Bill of Materials

TI DESIGNS

TIDM-TIA

Designator	Description	Comment	Quantity	Manufacturer	Manufacturer Part Number	Supplier Part Number	Footprint
C1	CAP, CERM, 0.01uF, 250V, +/-10%, X7R, 0805	DNP	1	Taiyo Yuden	QMK212B7103KG-T	587-1271-1-ND	0805_HV
C2, C4	CAP, TA, 10uF, 10V, +/-20%, 2.5 ohm, SMD	293D106X0010B2TE3	2	Vishay Sprague	293D106X0010B2TE3	718-1119-1-ND	3528-21
C3, C5	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0805	08053C104KAT2A	2	AVX Corporation	08053C104KAT2A	478-3755-1-ND	0805_HV
C6	CAP, CERM, 1pF, 50V, +/-25%, C0G/NP0, 0805	08055A1R0CAT2A	1	AVX Corporation	08055A1R0CAT2A	478-1292-1-ND	0805_HV
D1	LED, Green, SMD	LG L29K-G2J1-24-Z	1	OSRAM Opto Semiconductors Inc	LG L29K-G2J1-24-Z	475-2709-1-ND	LG L29K_GREEN
D2	OSRAM Photodiode	SFH 2701	1	OSRAM Opto Semiconductors Inc	SFH 2701	475-2967-X-ND	SFH 2701 - 1206
J1, J2, JP1, JP3, JP4	Header, 100mil, 3x1, Gold, TH	TSW-103-07-G-S	5	Samtec Inc	TSW-103-07-G-S	SAM1029-03-ND	TSW-103-07-G-S
J3, JP2	Header, 100mil, 2x1, Gold, TH	TSW-102-07-G-S	2	Samtec Inc	TSW-102-07-G-S	SAM1029-02-ND	TSW-102-07-G-S
JTAG	Header (shrouded), 100 mil, 7x2, Gold, TH	SBH11-PBPC-D07-ST-BK	1	Sullins Connector Solutions	SBH11-PBPC-D07-ST-BK	S9170-ND	CONN_SBH11-PBPC-D07-ST-BK
R1	RES, 560 ohm, 5%, 0.1W, 0603	CRCW0603560RJNEA	1	Vishay Dale	CRCW0603560RJNEA	541-560GCT-ND	0603
R2	RES, 47k ohm, 5%, 0.1W, 0603	CRCW060347K0JNEA	1	Vishay Dale	CRCW060347K0JNEA	541-47KGCT-ND	0603
R3	RES, 2.37Meg ohm, 1%, 0.1W, 0603	CRCW06032M37FKEA	1	Vishay Dale	CRCW06032M37FKEA	541-2.37MHCT-ND	0603
R4	RES	DNP	1				External Resistor
U1	16-bit Ultra-Low-Power Microcontroller, 32 KB Flash, 1 K RAM, RHA0040B	MSP430F2274IRHA	1	Texas Instruments	MSP430F2274IRHAT	296-21459-1-ND	RHA0040B

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